

ABSTRACT

BOND HEAD ASSEMBLIES, THERMOCOMPRESSSION BONDING SYSTEMS AND METHODS OF ASSEMBLING AND OPERATING THE SAME

A bond head assembly for bonding a semiconductor element to a substrate is provided. The bond head assembly includes a base structure, a heater, and a clamping system securing the heater to the base structure. The clamping system includes a plurality of elastic elements constraining the heater along a plurality of axes.

Fig. 1